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April 1st, 2010
Renesas Electronics Corporation

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SH7080 Group

Data Transfer Controller (DTC) in Chain Transfer Mode

Introduction

This application note describes the chain transfer mode of the data transfer controller (DTC). It is intended as reference material to help in the design of user software.

Target Device

SH7086

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1. Specification

In this sample application, ADI interrupt requests from the A/D converter of the SH7086 activate the DTC for data transfer in normal transfer mode.

A/D conversion is performed once on analog input channels 0 to 3 (AN0 to AN3) in continuous scan mode. The DTC transfers the converted data in ADDR0 to the on-chip RAM. After the data in ADDR0 have been transferred, the DTC transfers the converted data in ADDR1 to the RAM. An overview of the operation is presented in figure 1.

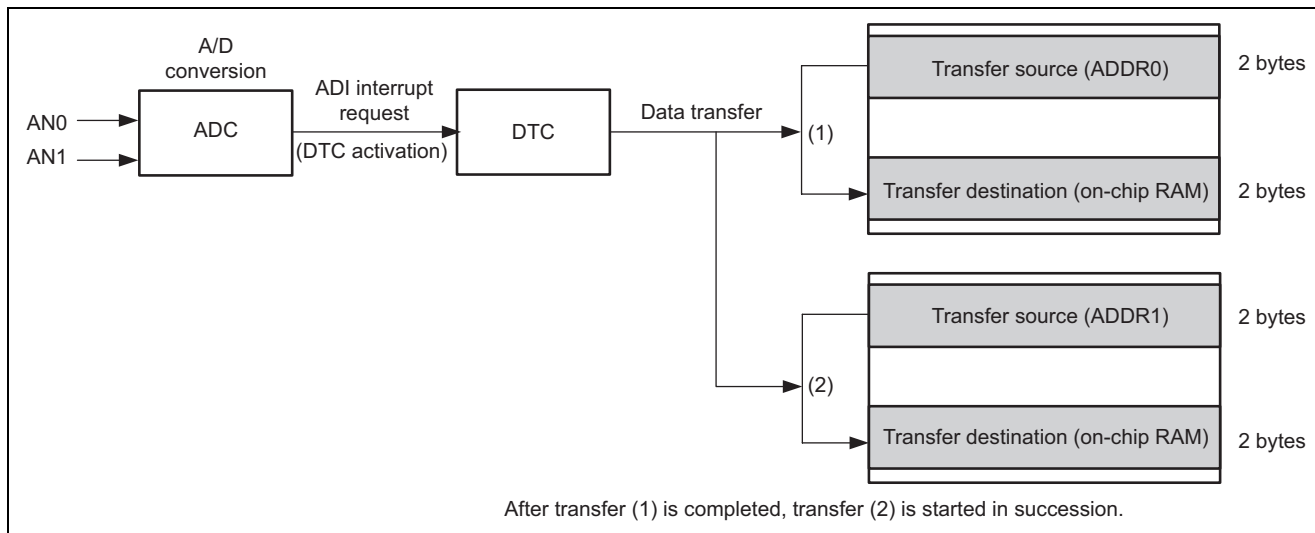


Figure 1 Overview of DTC Operation

2. Applicable Conditions

The applicable conditions for this sample application are shown in table 1.

Table 1 Applicable Conditions

Item	Setting
Device	SH7086 (R5F70865)
Operating frequency	Internal clock $I\phi = 80$ MHz Bus clock $B\phi = 40$ MHz Peripheral clock $P\phi = 40$ MHz MTU2 clock $MP\phi = 40$ MHz MTU2S clock $MI\phi = 80$ MHz
Operating mode	Single-chip mode
Development tool	High-performance Embedded Workshop Ver.4.03.00.001 (integrated development environment) SuperH RISC engine Standard Toolchain (V.9.1.1.0) SuperH RISC engine C/C++ Compiler (V.9.01.01) (manufactured by Renesas Technology)
C compiler options	High-performance Embedded Workshop default settings: [-cpu=sh2 -object="\$(CONFIGDIR)\\$(FILELEAF).obj" -debug -gbr=auto -chgincpath -errorpath -global_volatile=0 -opt_range=all -infinite_loop=0 -del_vacant_loop=0 -struct_alloc=1 -nologo]

3. Description of Modules Used

In this sample application, the DTC transfers data to the on-chip RAM when activated by an ADI interrupt request.

The functions of the DTC of SH7080 Group products are outlined in table 2.

Table 2 DTC Function Overview

Item	Overview
Number of channels	Transfer is possible any number of channels.
Chain transfer	Chain transfer is possible (data transfer can be performed multiple times in response to a single activation source). <ul style="list-style-type: none"> • Chain transfer is only possible after data transfer has been performed for the specified number of times (when the counter = 0).
Transfer mode	<ul style="list-style-type: none"> • Normal transfer, repeat transfer or block transfer mode can be selected. • Increment decrement or fixed can be selected for the source and destination addresses.
Address space	The transfer source and destination addresses can be specified by 32 bits to select a 4-Gbyte address space directly.
Transfer data size	Data transfer size can be specified by one byte, word or longword.
Interrupt source	<ul style="list-style-type: none"> • An interrupt request can be issued to the CPU after one data transfer completion. • An interrupt request can be issued to the CPU after all specified data transfer completion.
Bus release timing	Timing is selected from five types.
Priority of DTC activation	Priority of the DTC activation can be selected fro two types.
Others	<ul style="list-style-type: none"> • Read skip of the transfer-control information can be specified. • Writeback skip is executed for the fixed transfer source and destination addresses. • Module stop mode can be set. • Short address mode can be set.

A block diagram of the DTC is shown in figure 3.

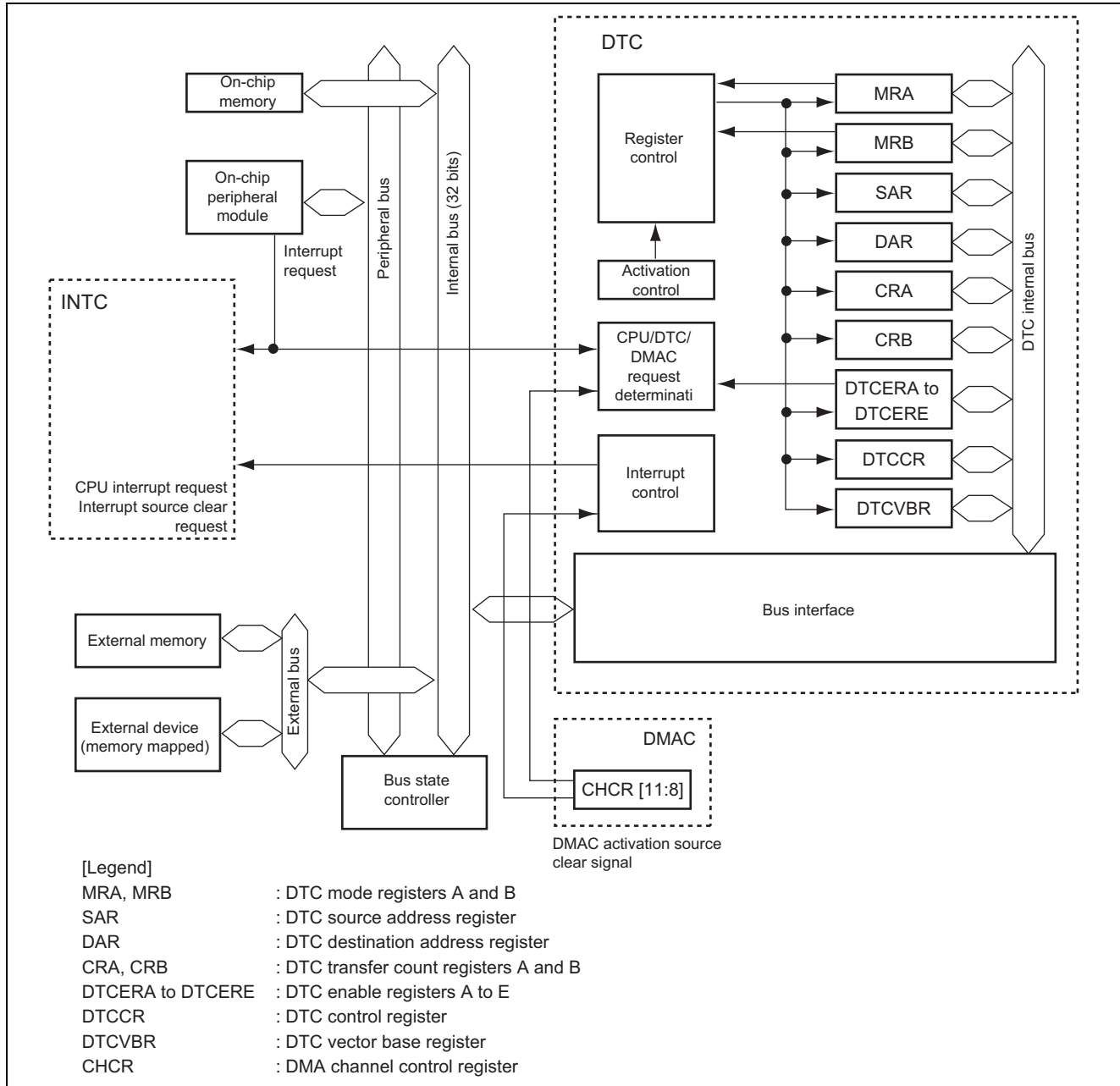


Figure 2 Block Diagram of the DTC

- DTC mode register A (MRA) and DTC mode register B (MRB)
MRA and MRB are 8-bit registers that control the operating mode of the DTC.
- DTC source address register (SAR)
SAR is a 32-bit register that designates the source address of data to be transferred by the DTC.
- DTC destination address register (DAR)
DAR is a 32-bit register that designates the destination address of data to be transferred by the DTC.
- DTC transfer count register A (CRA)
CRA is a 16-bit register that designates the number of times data is to be transferred by the DTC. In normal transfer mode, CRA functions as a 16-bit transfer counter (1 to 65,536). In repeat transfer mode, CRA is divided into two parts: the upper eight bits (CRAH) and the lower eight bits (CRAL). CRAH holds the number of transfers while CRAL functions as an 8-bit transfer counter. In block transfer mode, CRA is divided into two parts: the upper eight bits (CRAH) and the lower eight bits (CRAL). CRAH holds the block size while CRAL functions as an 8-bit block-size counter.
- DTC transfer count register (CRB)
CRB is a 16-bit register. In block transfer mode it specifies the number of times blocks are to be transferred.
- The DTC enable register (DTCER)
DTCER which is comprised of eight registers, DTCERA to DTCERE, is a 16-bit register that specifies DTC activation interrupt sources.
- The DTC control register (DTCCR)
DTCCR is an 8-bit register that specifies transfer information read skip.
- The DTC vector base register (DTCVBR)
DTCVBR is a 32-bit register that specifies the base address for vector table address calculation.
- Six registers, the DTC mode register (MRA), DTC mode register B (MRB), DTC source address register (SAR), DTC destination address register (DAR), DTC transfer count register A (CRA) and DTC transfer count register B (CRB) are not directly accessible from the CPU. When an event corresponding to a DTC activation source occurs, the necessary information for these registers is selected from the set of register information stored in the on-chip RAM and then transferred to the registers so that the DTC transfer can proceed. On completion of the transfer, the contents of these registers are written back to the on-chip RAM. Accordingly, you can have the user program store information for these registers in desired addresses within the on-chip RAM.

Note: For details on the operational specifications, see the section on the data transfer controller (DTC) in the SH7080 Group Hardware Manual.

4. Principles of Operation

Operations for this sample application are described below.

Figure 4 is a timing diagram for A/D conversion, DTC activation and data transfer. The processes are shown in table 3.

In this sample application, the ADI interrupt request is the DTC activation source. In addition, only channels AN0 and AN1 are used for DTC transfer although all A/D conversion proceeds on all of the specified channels (in this case, four channels) in continuous scan mode.

Firstly, the ADI interrupt is enabled, and then the ADST bit is set to 1 to start A/D conversion (figure 3, (1)). When the ADF bit is set to 1 automatically at the end of the A/D conversion, an ADI interrupt request is generated and the DTC is activated (figure 3, (2)). Even if an ADI interrupt request is generated, no interrupt occurs if the DTC is activated. Then, the DTC transfers A/D-converted data in ADDR0 to the previously reserved area in RAM (figure 3, (3)). After that, the DTC also transfers A/D-converted data in ADDR1 to the area in RAM in succession. When the data transfer ends, the ADF bit is automatically cleared (figure 3, (4)). The A/D conversion in this sample application is performed in continuous scan mode. Therefore, the ADST bit is not automatically cleared. When the DTC transfer ends and the ADF bit is set to 1, the DTCE bit is cleared automatically, thereby causing an ADI interrupt (figure 3, (5)). In the processing routine for this interrupt, the ADST bit is cleared to stop the A/D converter (figure 3, (6)).

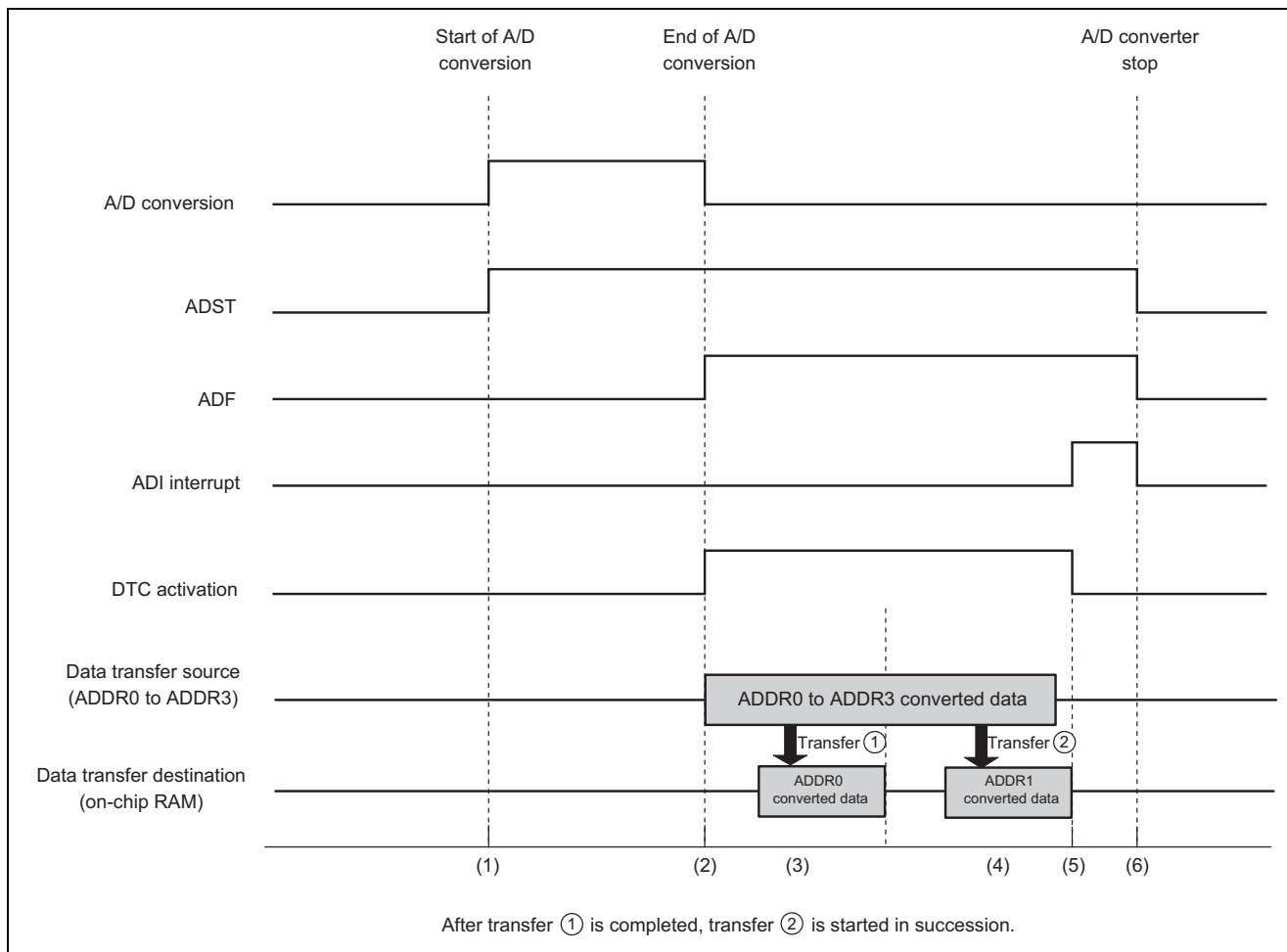


Figure 3 Timing of A/D Conversion and DTC Transfer

Table 3 Processes

	Software Processing	Hardware Processing
(1)	Enable an ADI interrupt. Set the ADST bit to 1 (for start A/D conversion).	—
(2)	—	Set the ADF bit to 1. Generate an ADI interrupt request. Activate the DTC.
(3)	—	Transfer data from ADDR0 to the RAM area.
(4)	—	Transfer data from ADDR1 to the RAM area.
(5)	—	Set the ADF bit to 1. Clear the DTCE bit to 0. Generate an ADI interrupt.
(6)	Clears the ADST bit (to stop the A/D converter).	—

A more detailed timing diagram of the DTC transfer operations is given as figure 4.

In DTC transfer, DTC activation sources (in this case, ADI interrupt request) generate DTC requests. Mastership of the internal bus is secured and the DTC is activated (figure 4(1)). The address where the control information for the transfer starts is read from the vector table of ADI activation sources (figure 4 (2)) that has been set up for this example. The information is then read, starting at the given address (figure 4 (3)). After that, the data is transferred from the source address (ADDR0) to the destination address (on-chip RAM) (figure 4 (4)). The transfer control information is then written back (figure 4 (5)). This is followed by reading of the next set of transfer control information after which the data from the source for the next transfer (ADDR1) are transferred to the destination address (in the on-chip RAM) (figure 4 (6)). The ADF bit is automatically cleared in response to reading of the ADDR (figure 4 (7)).

Finally, the control information for the transfer is written back (figure 4 (8)). The DTC releases the bus after the writeback operation (figure 4 (9)).

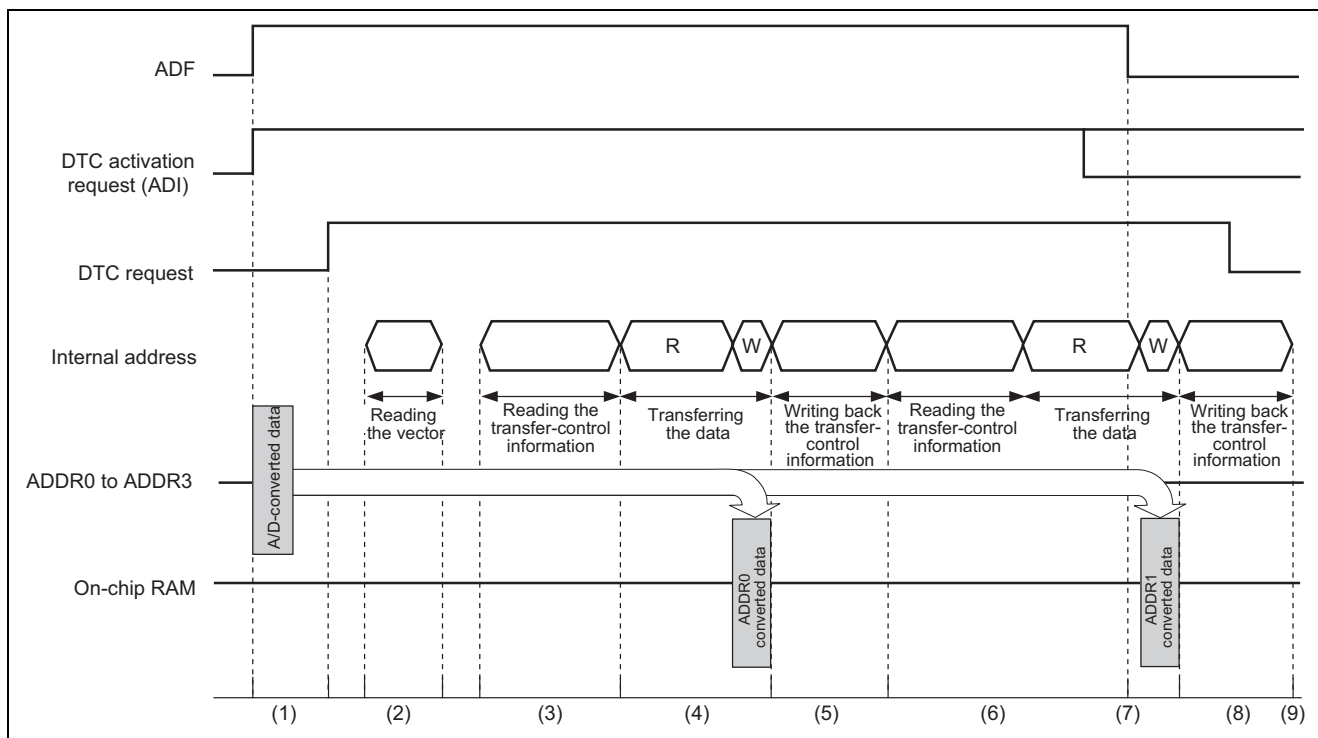


Figure 4 Detailed Timing Chart of DTC Transfer

The flow of data in memory for the operations shown in zones (2) to (6) of figure 4 is illustrated in figure 5 and described in table 4.

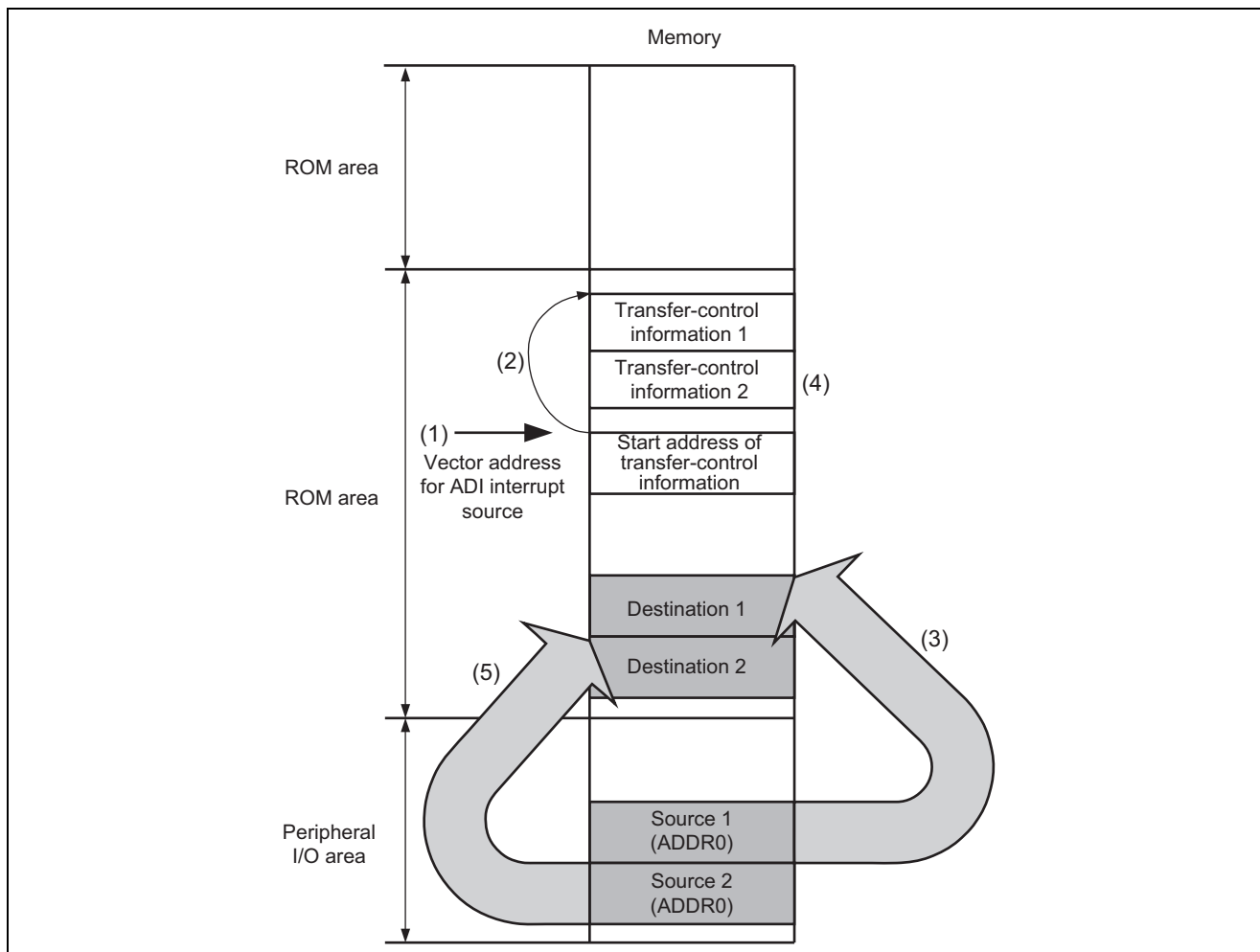


Figure 5 Flow of Data in Memory

Table 4 Description of Figure 5

DTC Function	
(1)	Reads the address (base address + H'400 + interrupt source (ADI) vector number × 4) of the transfer-control information from the vector for this activation source (ADI).
(2)	Reading of the transfer-control information 1 This information specifies the data size, source address, destination address, etc. for the first transfer
(3)	Transfers the amount of data specified as the size by the transfer-control information 1 from the source address 1 (ADDR0) to the destination address 1 (in RAM).
(4)	Reading of the transfer-control information 2 This information specifies the data size, source address, destination address, etc. for the second transfer
(5)	Transfers the amount of data specified as the size by the transfer-control information 2 from the source address 2 (ADDR0) to the destination address 2 (in RAM).

5. Description of Software

5.1 List of Functions

The functions used in this sample application are listed below.

Table 5 List of Functions

Function Name	Description
main()	Performs DTC transfer and calls the A/D conversion routine.
ad_conv()	A/D conversion routine
INT_AD0_ADI0 ()	ADI interrupt routine

5.2 Variables Used

The variables used in this sample application are listed below.

Table 6 List of Variables

Variable/Label Name	Description	Reference Function
unsigned short D_data[DTC_COUNT]	Array (of 2-byte elements) for storing transferred data. DTC_COUNT is the number of times transfer is to proceed, i.e. 2 for this sample application.	main()
unsigned short dummy	Variable for reading the interrupt source bit	main()

5.3 Section Settings

The sections of the program for this sample application are assigned as shown below.

The vector for a DTC activation source used in this sample application is as follows.

Table 7 Section Settings

Address	Section Name	Description
H'00000000	DVECTTBL, DINTTBL, PIntPRG	DVECTTBL: Exception vector table DINTTBL: Interrupt vector table PIntPRG: Interrupt program
H'00000800	PResetPRG	Reset program
H'00001000	P, C\$BSEC, C\$DEC, D	P: Program area C\$BSEC: Holds an address for B section initialization. C\$DEC: Holds an address for D section initialization. D: Holds data.
H'FFFF4000	B, R	B: uninitialized data area. R: initialized data area.
H'FFFF6720	DDTC_AD0_ADI	Vector for the DTC activation source (ADI interrupt requests)
H'FFFFBC00	S	Stack area

5.4 Register Settings

The registers used in this sample application are described below. The settings below are the values used in this application and differ from the initial values.

5.4.1 Clock Oscillator (CPG) Settings

1. Frequency Control Register (FRQCR)

Function: Specifies the frequency division ratios for the internal clock ($I\phi$), bus clock ($B\phi$), peripheral clock ($P\phi$), MTU2S clock ($MI\phi$), and MTU2 clock ($MP\phi$).

Set value: H'0241

Bit	Bit Name	Set Value	Description
15	—	0	Reserved
14 to 12	IFC[2:0]	000	Internal Clock ($I\phi$) Frequency Division Ratio 000: $\times 1$ ($I\phi = 80$ MHz for an input clock frequency of 10 MHz)
11 to 9	BFC[2:0]	001	Bus Clock ($B\phi$) Frequency Division Ratio 001: $\times 1/2$ ($B\phi = 40$ MHz for an input clock frequency of 10 MHz)
8 to 6	PFC[2:0]	001	Peripheral Clock ($P\phi$) Frequency Division Ratio 001: $\times 1/2$ ($P\phi = 40$ MHz for an input clock frequency of 10 MHz)
5 to 3	MIFC[2:0]	000	MTU2S Clock ($MI\phi$) Frequency Division Ratio 000: $\times 1$ ($MI\phi = 80$ MHz for an input clock frequency of 10 MHz)
2 to 0	MPFC[2:0]	001	MTU2 Clock ($MP\phi$) Frequency Division Ratio 001: $\times 1/2$ ($MP\phi = 40$ MHz for an input clock frequency of 10 MHz)

5.4.2 Power-Down Mode Settings

1. Standby Control Register 2 (STBCR2)

Function: Controls the operation of individual modules in power-down mode.
Set value: H'28

Bit	Bit Name	Set Value	Description
7	MSTP7	0	Module Stop Bit 7 When set to 1, stops the clock supply to the to the on-chip RAM. When set to 0, activates the on-chip RAM.
6	MSTP6	0	Module Stop Bit 6 When set to 1, stops the clock supply to the to the ROM. When set to 0, activates the ROM.
5	—	1	Reserved
4	MSTP4	0	Module Stop Bit 4 When set to 1, stops the clock supply to the to the DTC. When set to 0, activates the DTC.
3	MSTP3	1	Module Stop Bit 3 When set to 1, stops the clock supply to the to the DMAC. When set to 0, activates the DMAC.
2 to 0	—	All 0	Reserved

2. Standby Control Register 4 (STBCR4)

Function: Controls the operation of individual modules in power-down mode.
Set value: H'FE

Bit	Bit Name	Set Value	Description
7	MSTP23	1	Module Stop Bit 23 When set to 1, stops the clock supply to the to the MTU2S. When set to 0, activates the MTU2S.
6	MSTP22	1	Module Stop Bit 22 When set to 1, stops the clock supply to the to the MTU2. When set to 0, activates the MTU2.
5	MSTP21	1	Module Stop Bit 21 When set to 1, stops the clock supply to the to the CMT. When set to 0, activates the CMT.
4, 3	—	All 1	Reserved
2	MSTP18	1	Module Stop Bit 18 When set to 1, stops the clock supply to the to the AD_2. When set to 0, activates the AD_2.
1	MSTP17	1	Module Stop Bit 17 When set to 1, stops the clock supply to the to the AD_1. When set to 0, activates the AD_1.
0	MSTP16	0	Module Stop Bit 16 When set to 1, stops the clock supply to the to the AD_0. When set to 0, activates the AD_0.

5.4.3 Interrupt Controller Settings

1. Interrupt Priority Register K (IPRK)

Function: Sets priority levels for interrupt sources.
Set value: H'F000

Bit	Bit Name	Set Value	Description
15 to 12	A/D0, 1	All 1	Set the priority level of the A/D0 and A/D1 interrupt sources. (The maximum value, 15, is set in this sample application).
11 to 8	A/D2	All 0	Set the priority level of the A/D2 interrupt source. (The initial value is set in this sample application).
7 to 0	—	All 0	Reserved

5.4.4 DTC Settings

1. DTC Mode Register A (MRA)

Function: Selects DTC operating mode. MRA cannot be accessed directly by the CPU. Transfer-control information should be stored in the on-chip RAM.

Set value: H'10

Bit	Bit Name	Set Value	Description
7, 6	MD[1:0]	00	DTC Mode 1/0 Specifies DTC transfer mode. (Normal transfer mode is specified in this sample application.)
5, 4	Sz[1:0]	01	DTC Data Transfer Size 1 and 0 Specifies the size of data to be transferred. (One word is specified in this sample application.)
3, 2	SM[1:0]	00	Source Address Mode 1 and 0 Specifies an SAR operation after a data transfer. (SAR is fixed after transfer in this sample application.)
1, 0	—	All 0	Reserved

2. DTC Mode Register B (MRB)

Function: Selects operating mode. MRB cannot be accessed directly by the CPU. Transfer-control information should be stored in the on-chip RAM.

Chain transfer (first transfer) settings

Set value: H'C8

Bit	Bit Name	Set Value	Description
7	CHNE	0	DTC Chain Transfer Enable Specifies the chain transfer. (Chain transfer is enabled in this sample application.)
6	CHNS	0	DTC Chain Transfer Select Selects conditions of chain transfer. (In this sample application, chain transfer proceeds when the transfer counter is 0.)
5	DISEL	0	DTC Interrupt Select When this bit is set to 1, an interrupt request is issued to the CPU after each data transfer or block transfer. When this bit is set to 0, an interrupt request is issued to the CPU after data transfer has been completed for the specified number of times.
4	DTS	0	DTC Transfer Mode Select Specifies either the source or destination as repeat or block area during repeat or block transfer mode. (used in the case of repeat transfer and block transfer modes.)
3, 2	DM[1:0]	10	Destination Address Mode 1 and 0 Specifies the DAR operation after data transfer. (The DAR is incremented after transfer in case of this sample application.)
1, 0	—	00	Reserved

Settings after chain transfer (second transfer)

Set value: H'08

Bit	Bit Name	Set Value	Description
7	CHNE	0	DTC Chain Transfer Enable Specifies the chain transfer. (Chain transfer is disabled for this sample application.)
6	CHNS	0	DTC Chain Transfer Select Specifies the chain transfer condition. (Used in case of chain transfer.)
5	DISEL	0	DTC Interrupt Select When this bit is set to 1, an interrupt request is issued to the CPU after each data transfer or block transfer. When this bit is set to 0, an interrupt request is issued to the CPU after data transfer has been completed for the specified number of times.
4	DTS	0	DTC Transfer Mode Select Specifies either the source or destination as repeat or block area during repeat or block transfer mode. (Used in the case of repeat transfer and block transfer modes.)
3, 2	DM[1:0]	10	Destination Address Mode 1 and 0 Specifies the DAR operation after data transfer. (The DAR is incremented after transfer in case of this sample application.)
1, 0	—	00	Reserved

3. DTC Source Address Register (SAR)

Function: Designates the source address of data to be transferred by the DTC. SAR cannot be accessed directly by the CPU. Transfer-control information should be stored in the on-chip RAM.

Chain transfer (first transfer) settings

Set value: H'FFFC900 (&AD0.ADDR0)

Settings after chain transfer (second transfer)

Set value: H'FFFC902 (&AD0.ADDR1)

4. DTC Destination Address Register (DAR)

Function: Designates the source address of data to be transferred by the DTC. DAR cannot be accessed directly by the CPU. Transfer-control information should be stored in the on-chip RAM.

Chain transfer (first transfer) settings

Set value: H'FFF4420 (&(D_data[0]))

Settings after chain transfer (second transfer)

Set value: H'FFF4422 (&(D_data[1]))

5. DTC Transfer Count Register (CRA)

Function: Specifies the DTC data transfer count.

In normal transfer mode, CRA functions as a 16-bit transfer counter (1 to 65,536). It is decremented by 1 every time data is transferred, and bit DTCE_n (n = 15 to 0) corresponding to the activation source is cleared and then an interrupt is requested to the CPU when the count reaches H'0000. The transfer count is 1 when CRA = H'0001, 65,535 when CRA = H'FFFF, and 65,536 when CRA = H'0000.

CRA cannot be accessed directly by the CPU. Transfer-control information should be stored in the on-chip RAM.

Chain transfer (first transfer) settings

Set value: H'0001 (once)

Settings after chain transfer (second transfer)

Set value: H'0001 (once)

6. DTC Transfer Count Register B (CRB)

Function: Designates the number of times data is to be transferred by the DTC in block transfer mode. CRB cannot be accessed directly by the CPU. Transfer-control information should be stored in the on-chip RAM.

Since there is no block transfer in this sample application the initial values are left intact.

Set value: H'0000 (initial value)

7. DTC Enable Register D (DTCERD)

Function: Selects an interrupt source for activating the DTC. The other DTC enable registers are not used for this sample application.

The clearing and setting conditions for each bit in the DTECERD are shown below.

[Clearing conditions]

- Writing 0 to the it after reading it as 1
- Completion of one data transfer and the DISEL bit in MRB = 1
- Completion of the specified number of transfers

[Setting conditions]

- Writing 1 to the bit after reading it as 0

Set value: H'0020

Bit	Bit Name	Set Value	Description
15	DTCERD15	0	When set to 1, selects TGIA_4S as the DTC activation source.
14	DTCERD14	0	When set to 1, selects TGIB_4S as the DTC activation source.
13	DTCERD13	0	When set to 1, selects TGIC_4S as the DTC activation source.
12	DTCERD12	0	When set to 1, selects TGID_4S as the DTC activation source.
11	DTCERD11	0	When set to 1, selects TGIV_4S as the DTC activation source.
10	DTCERD10	0	When set to 1, selects TGIU_4S as the DTC activation source.
9	DTCERD9	0	When set to 1, selects TGIV_4S as the DTC activation source.
8	DTCERD8	0	When set to 1, selects TGIW_4S as the DTC activation source.
7	DTCERD7	0	When set to 1, selects CMI_0 as the DTC activation source.
6	DTCERD6	0	When set to 1, selects CMI_1 as the DTC activation source.
5	DTCERD5	1	When set to 1, selects ADI_0 as the DTC activation source.
4	DTCERD4	0	When set to 1, selects ADI_1 as the DTC activation source.
3	DTCERD3	0	When set to 1, selects ADI_2 as the DTC activation source.
2 to 0	—	All 0	Reserved

8. DTC Control Register (DTCCR)

Function: Specifies transfer-control information read skip.
Set value: H'00

Bit	Bit Name	Set Value	Description
7 to 5	—	All 0	Reserved
4	RRS	0	DTC Transfer-Control information Read Skip Enable Controls the vector address read and transfer-control information read. A DTC vector number is always compared with the vector number for the previous activation. If the vector numbers match and this bit is set to 1, the DTC data transfer is started without reading a vector address and Transfer-control information. If the previous DTC activation is a chain transfer, the vector address read and transfer-control information read are always performed.
3	RCHNE	0	Chain Transfer Enable After DTC Repeat Transfer Enables or disables chain transfer while transfer counter is 0 in repeat transfer mode.
2, 1	—	All 0	Reserved
0	ERR	0	Transfer Stop Flag Indicates that the DTC address error or NMI request has occurred. If a DTC address error or NMI occurs while the DTC is active, address error handling or NMI handling processing is executed after the DTC has released the bus mastership. The DTC stops in the transfer-control information writing state after transferring data. [Clearing condition] <ul style="list-style-type: none"> • Writing of 0 to this bit after reading it as 1

9. DTC Vector Base Register (DTCVBR)

Function: Specifies the base address for vector table address calculation.
Set value: H'FFFF6000

10. Bus Function Extending Register (BSCEHR)

Function: This register sets the DTC bus release timing, etc.

Set value: BSCEHR is not set in this sample application and the initial values are used on an as-is basis.

Bit	Bit Name	Initial Value	Description
15	DTLOCK	0	DTC Lock Enable Specifies the timing of bus release by the DTC.
14	CSSTP1	0	Select Bus Release on NOP Cycle Generation by DTC Specifies whether or not the bus is released in response to requests from the CPU for external space access on generation of the NOP cycle that follows reading of the vector address.
13	—	0	Reserved
12	CSSTP2	0	Select Bus Release during Burst-Mode-DMAC/DTC Transfer
11	DTBST	0	DTC Burst Enable Selects whether or not the DTC retains the bus mastership and remains continuously active until all transfer operations are complete when multiple DTC activation requests have been generated.
10	DTSA	0	DTC Short Address Mode Designates whether the information that specifies a DTC transfer takes up 3 or 4 longwords.
9	CSSTP3	0	Select Priority for External Memory Access by CPU
8	DTPR	0	Application of Priority in DTC Activation When multiple DTC activation requests are generated before the DTC is activated, specify whether transfer starts from the first request to have been generated or is in accord with the priority order for DTC activation requests. However, when multiple DTC
7 to 5	—	All 0	Reserved
4	DMMTU4	0	Enable Burst-Mode DMAC Transfer with TGIA_4 Activation Source
3	DMMTU3	0	Enable Burst-Mode DMAC Transfer with TGIA_3 Activation Source
2	DMMTU2	0	Enable Burst-Mode DMAC Transfer with TGIA_2 Activation Source
1	DMMTU1	0	Enable Burst-Mode DMAC Transfer with TGIA_1 Activation Source
0	DMMTU0	0	Enable Burst-Mode DMAC Transfer with TGIA_0 Activation Source

5.4.5 A/D Conversion Settings

1. A/D Control/Status Register_0 (ADCSR_0)

Function: Controls A/D conversion and sets A/D conversion time.

Set value: H'401B

Bit	Bit Name	Set Value	Description
15	ADF	0	A/D End Flag A status flag that indicates the end of A/D conversion. [Setting condition] • End of A/D conversion on all the channels in scan mode [Clearing conditions] • Writing of 0 to this bit after reading it as 1 • DMAC or DTC activation by an ADI interrupt to read ADDR
14	ADIE	1	A/D Interrupt Enable When set to 1, generation of an ADI interrupt by ADF is enabled.
13, 12	—	All 0	Reserved
11	TRGE	0	Trigger Enable Disables triggering of A/D conversion when TRGE = 1.
10	—	0	Reserved
9	CONADF	0	ADF Control Controls setting of the ADF bit in 2-channel scan mode.
8	STC	0	State Control Sets the A/D conversion time. (50 cycles is set in this sample application.)
7, 6	CKSL[1:0]	00	Clock Select 1 and 0 Select the A/D conversion time. (Pφ/4 is set in this sample application.)
5, 4	ADM[1:0]	01	A/D Mode 1 and 0 Select the A/D conversion mode. (4-channel scan mode is selected in this sample application.)
3	ADCS	1	A/D Continuous Scan Continuous scan mode is selected in this sample application.
2 to 0	CH[2:0]	011	Channel Select 2 to 0 Select analog input channels for A/D conversion. (Channels AN0 to AN3 are selected in this sample application.)

2. A/D Control Register_0 (ADCR_0)

Function: Controls A/D conversion.
Set value: H'0000

Bit	Bit Name	Set Value	Description
15, 14	—	All 0	Reserved
13	ADST	0	A/D Start When cleared to 0, A/D conversion is stopped and the A/D converter enters the idle state. When set to 1, A/D conversion is started. Cleared to 0 automatically in single mode when A/D conversion end on the selected single channel.
12 to 0	—	All 0	Reserved

3. A/D Trigger Select Register_0 (ADTSR_0)

Function: Enables an A/D conversion started by an external trigger signal.
Set value: H'0000 (initial value)

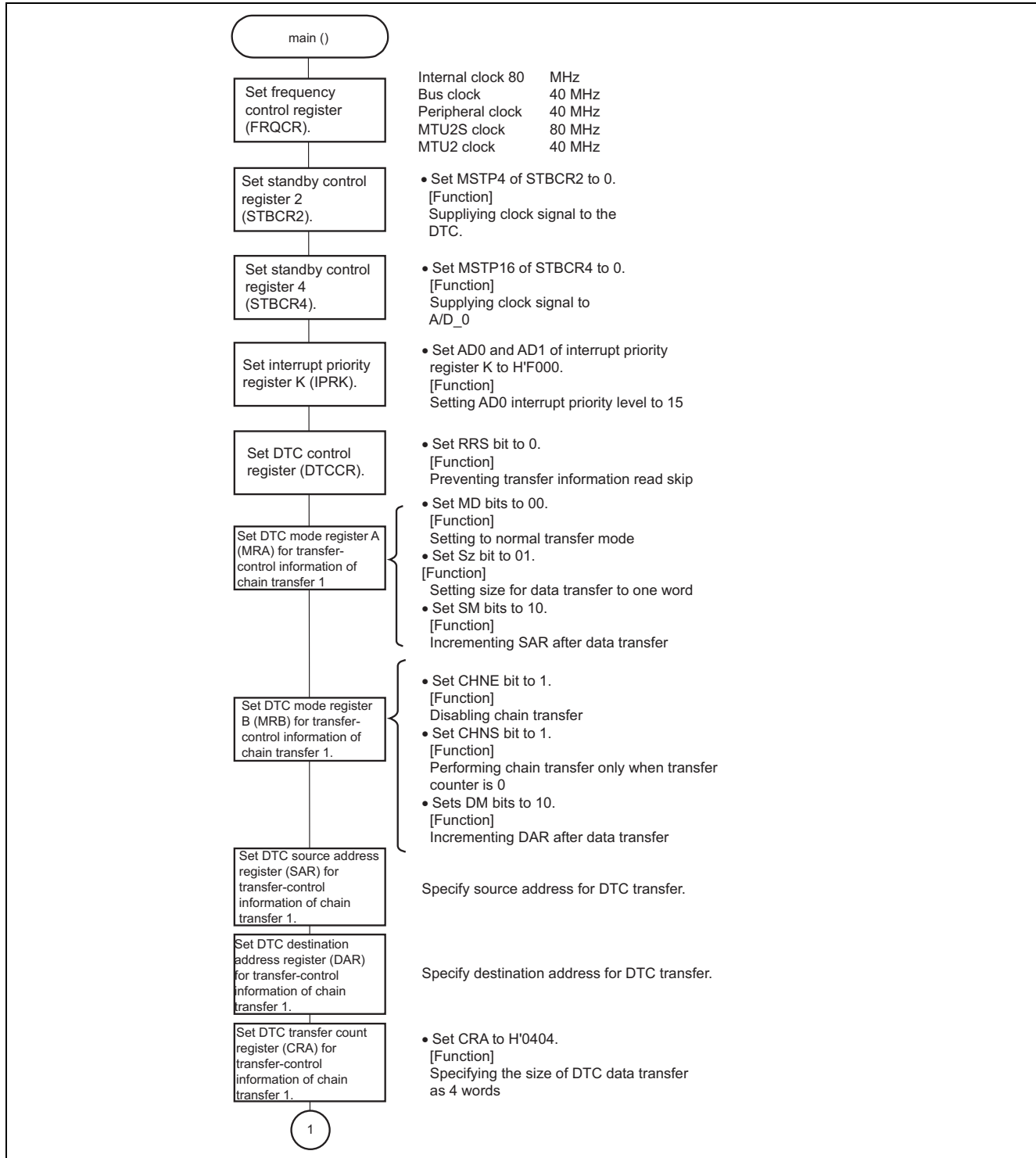
An external trigger signal is not used in this sample application. Thus, ADSTR_0 is not set and its the values are used on an as-is basis.

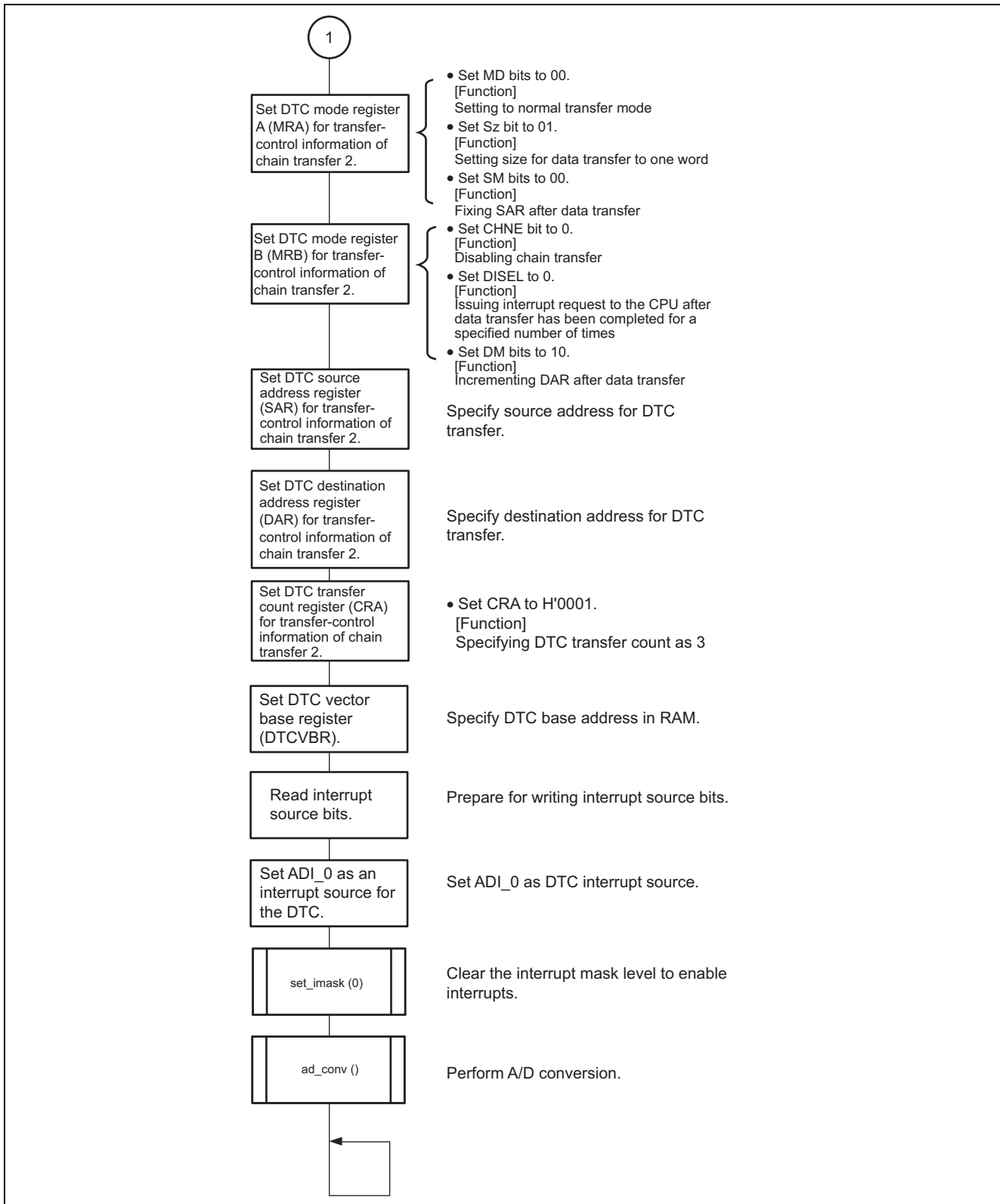
Bit	Bit Name	Initial Value	Description
15 to 12	TRG11S[3:0]	0000	A/D Trigger 1 Group 1 Select 3 to 0 Select an external trigger, MTU2 trigger or MTU2S trigger to start A/D conversion for group 1 when A/D module 1 is in 2-channel scan mode.
11 to 8	TRG01S[3:0]	0000	A/D Trigger 0 Group 1 Select 3 to 0 Select an external trigger, MTU2 trigger or MTU2S trigger to start A/D conversion for group 1 when A/D module 0 is in 2-channel scan mode.
7 to 4	TRG1S[3:0]	0000	A/D Trigger 1 Select 3 to 0 Select an external trigger, MTU2 trigger or MTU2S trigger to start A/D conversion for A/D module 1.
3 to 0	TRG0S[3:0]	0000	A/D Trigger 0 Select 3 to 0 Select an external trigger, MTU2 trigger or MTU2S trigger to start A/D conversion for A/D module 1.

6. Flowcharts

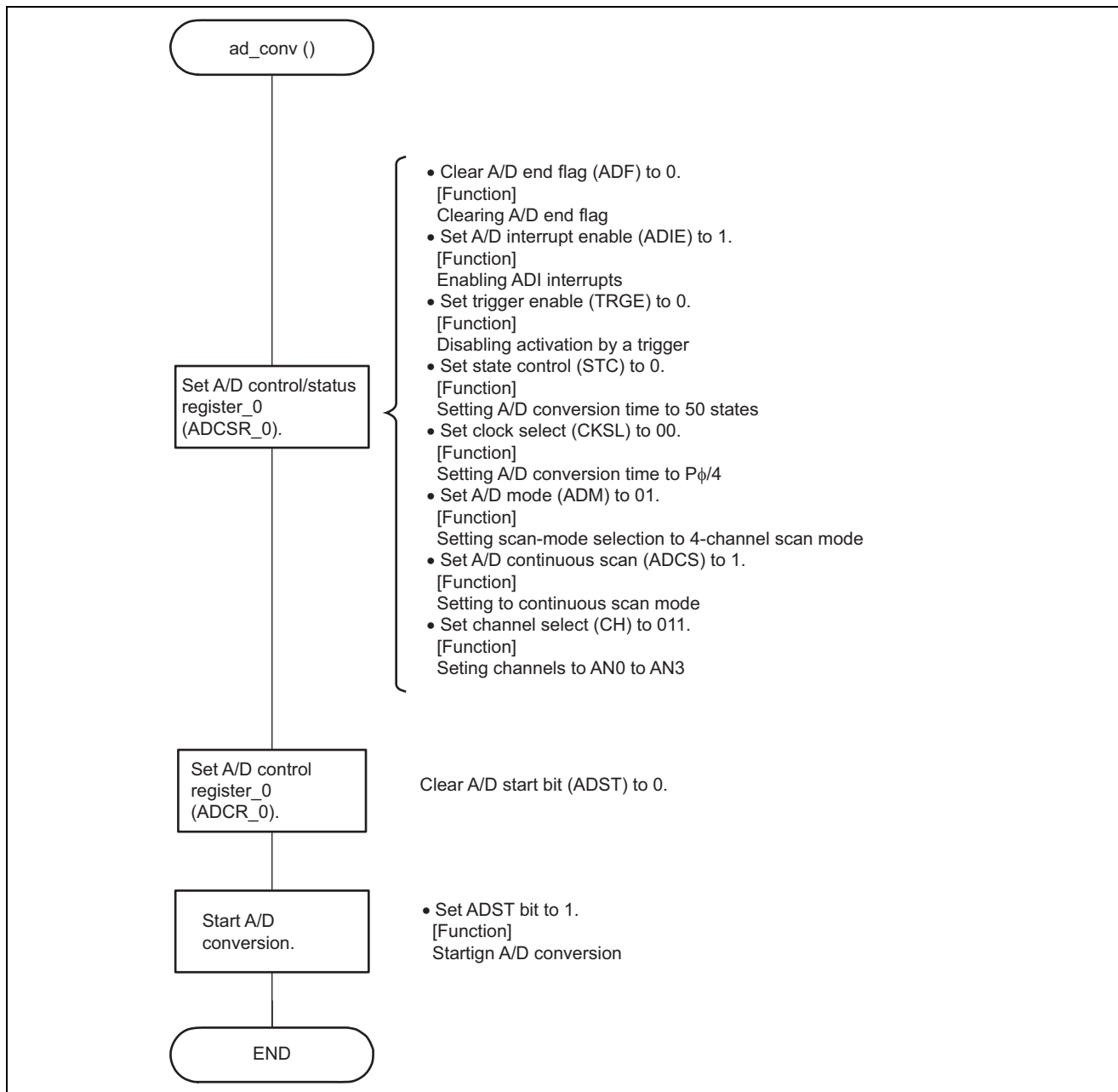
Flowcharts for this sample application are given below.

6.1 Main Routine

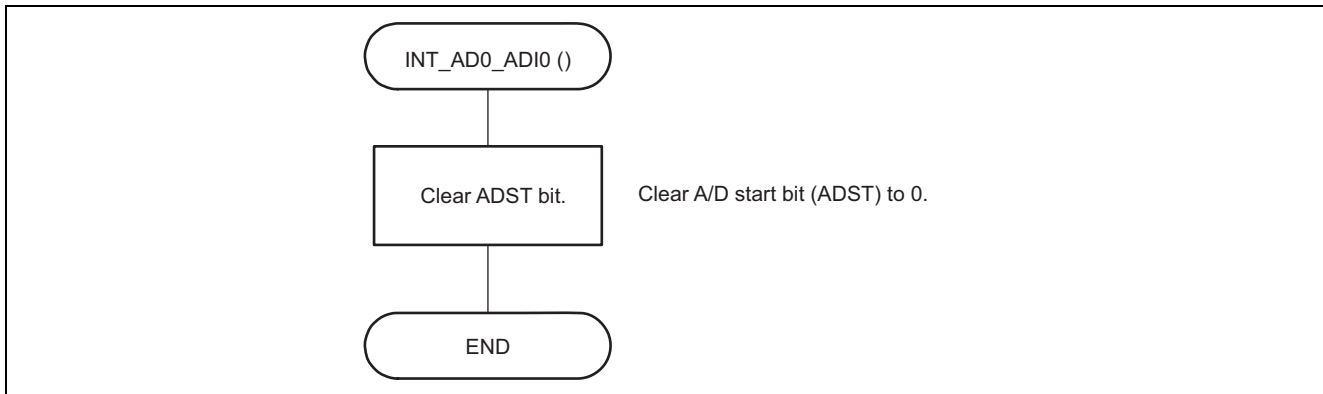




6.2 A/D Conversion Routine



6.3 ADI Interrupt Routine



7. Documents for Reference

- Software Manual
SH-1/SH-2/SH-DSP Software Manual
The most up-to-date version of this document is available on the Renesas Technology Website.
- Hardware Manual
SH7080 Group Hardware Manual
The most up-to-date version of this document is available on the Renesas Technology Website.

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Revision Record

Rev.	Date	Description	
		Page	Summary
1.00	Jan.18.08	—	First edition issued

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